NL17SZ07

Single Non-Inverting Buffer with Open Drain Output

The NL17SZ07 is a high performance single inverter with open drain outputs operating from a 1.65 to 5.5 V supply.

The Output stage is open drain with Over Voltage Tolerance. This allows the NL17SZ07 to be used to interface 5.0 V circuits to circuits of any voltage between 0 and +7.0 V.

- Tiny SOT−353 and SOT−553 Packages
- Extremely High Speed: t_{PD} 2.5 ns (typical) at V_{CC} = 5 V
- Designed for 1.65 V to 5.5 V V_{CC} Operation, CMOS Compatible
- Over Voltage Tolerant Inputs V_{IN} may be Between 0 and 7.0 V for V_{CC} Between 0.5 and 5.4 V
- TTL Compatible − Interface Capability with 5.0 V TTL Logic with V_{CC} = 2.7 V to 3.6 V
- LVCMOS Compatible
- 24 mA Output Sink Capability, Pullup may be between 0 and 7.0 V
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
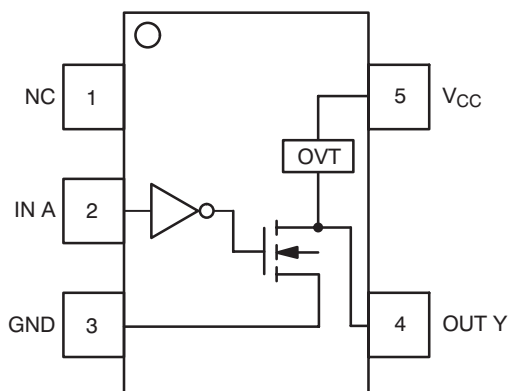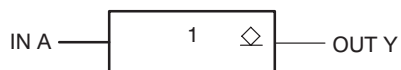- Chip Complexity: FET = 20
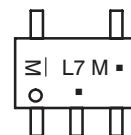- Pb−Free Packages are Available

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http://onsemi.com

Figure 1. Pinout

Figure 2. Logic Symbol

PIN ASSIGNMENT

Pin	Function
1	NC
2	IN A
3	GND
4	OUT Y
5	V_{CC}

FUNCTION TABLE

A Input	Y Output
L	L
H	Z

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

NL17SZ07

MAXIMUM RATINGS

Symbol	Characteristics		Value	Unit
V_{CC}	DC Supply Voltage		-0.5 to $+7.0$	V
V_I	DC Input Voltage		$-0.5 \leq V_I \leq +7.0$	V
V_O	DC Output Voltage	Output in Z or LOW State (Note 1)	$-0.5 \leq V_O \leq 7.0$	V
I_{IK}	DC Input Diode Current	$V_I < GND$	-50	mA
I_{OK}	DC Output Diode Current	$V_O < GND$	-50	mA
I_O	DC Output Sink Current		± 50	mA
I_{CC}	DC Supply Current per Supply Pin		± 100	mA
I_{GND}	DC Ground Current per Ground Pin		± 100	mA
T_{STG}	Storage Temperature Range		-65 to $+150$	°C
P_D	Power Dissipation in Still Air	SOT−353 SOT−553	186 135	mW
θ_{JA}	Thermal Resistance	SOT−353 SOT−553	350 496	°C/W
T_L	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
T_J	Junction Temperature Under Bias		$+150$	°C
$I_{Latch-Up}$	Latch−Up Performance	Above V_{CC} and Below GND at 85°C (Note 5)	± 500	mA
MSL	Moisture Sensitivity		Level 1	
F_R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V−0 @ 0.125 in	
ESD	ESD Classification	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	Class IC Class A N/A	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.
1. I_O absolute maximum rating must be observed.
2. Tested to EIA/JESD22−A114−A, rated to EIA/JESD22−A114−B.
3. Tested to EIA/JESD22−A115−A, rated to EIA/JESD22−A115−A.
4. Tested to JESD22−C101−A.
5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V_{CC}	Supply Voltage	Operating Data Retention Only	1.65 1.5	5.5 5.5	V
V_I	Input Voltage		0	5.5	V
V_O	Output Voltage	(Z or LOW State)	0	5.5	V
T_A	Operating Free−Air Temperature		−55	$+125$	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate	$V_{CC} = 2.5$ V ± 0.2 V $V_{CC} = 3.0$ V ± 0.3 V $V_{CC} = 5.0$ V ± 0.5 V	0 0 0	20 10 5	ns/V

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V_{CC} (V)	$T_A = 25°C$			$-55°C \leq T_A \leq 125°C$		Unit
				Min	Typ	Max	Min	Max	
V_{IH}	High–Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.7 V_{CC} 0.7 V_{CC}			0.7 V_{CC} 0.7 V_{CC}		V
V_{IL}	Low–Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.3 V_{CC} 0.3 V_{CC}		0.3V_{CC} 0.3 V_{CC}	V
I_{LKG}	Z–State Output Leakage Current	$V_{IN} = V_{IH}$ $V_{OUT} = V_{CC}$ or GND	2.3 to 5.5			± 5.0		± 10.0	μA
V_{OL}	Low–Level Output Voltage $V_{IN} = V_{IL}$	$I_{OL} = 100$ μA	1.65 to 5.5		0.0	0.1		0.1	V
		$I_{OL} = 4$ mA	1.65		0.08	0.24		0.24	
		$I_{OL} = 8$ mA	2.3		0.20	0.3		0.3	
		$I_{OL} = 12$ mA	2.7		0.22	0.4		0.4	
		$I_{OL} = 16$ mA	3.0		0.28	0.4		0.4	
		$I_{OL} = 24$ mA	3.0		0.38	0.55		0.55	
		$I_{OL} = 32$ mA	4.5		0.42	0.55		0.55	
I_{IN}	Input Leakage Current	V_{IN} or $V_{OUT} = V_{CC}$ or GND	0 to 5.5			± 0.1		± 1.0	μA
I_{OFF}	Power Off–Output Leakage Current	$V_{OUT} = 5.5$ V	0			1		10	μA
I_{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1		10	μA
I_{CCT}	Quiescent Supply Current	$V_{IN} = 3.0$ V	3.6			10		100	μA

AC ELECTRICAL CHARACTERISTICS $t_R = t_F = 2.5$ ns; $C_L = 50$ pF; $R_L = 500$ Ω

Symbol	Parameter	Condition	V_{CC} (V)	$T_A = 25°C$			$-55°C \leq T_A \leq 125°C$		Unit
				Min	Typ	Max	Min	Max	
t_{PZL}	Propagation Delay (Figure 3 and 4)	$R_L = R_1 = 500$ Ω, $C_L = 50$ pF	1.8 ± 0.15	0.8	5.3	11.6	0.8	12.0	ns
			2.5 ± 0.2	1.2	3.7	5.8	1.2	6.4	
			3.3 ± 0.3	0.8	2.9	4.4	0.8	4.8	
			5.0 ± 0.5	0.5	2.3	3.5	0.5	3.9	
t_{PLZ}	Propagation Delay (Figure 3 and 4)	$R_L = R_1 = 500$ Ω, $C_L = 50$ pF	1.8 ± 0.15	0.8	5.3	11.6	0.8	1.20	ns
			2.5 ± 0.2	1.2	2.8	5.8	1.2	6.4	
			3.3 ± 0.3	0.8	2.1	4.4	0.8	4.8	
			5.0 ± 0.5	0.5	1.4	3.5	0.5	3.9	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C_{IN}	Input Capacitance	$V_{CC} = 5.5$ V, $V_I = 0$ V or V_{CC}	> 2.5	pF
C_{OUT}	Output Capacitance	$V_{CC} = 5.5$ V, $V_I = 0$ V or V_{CC}	4.0	pF
C_{PD}	Power Dissipation Capacitance (Note 6)	10 MHz, $V_{CC} = 5.5$ V, $V_I = 0$ V or V_{CC}	4.0	pF

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

NL17SZ07
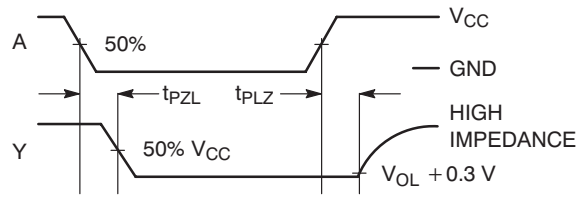
Figure 3. Switching Waveforms

$R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)
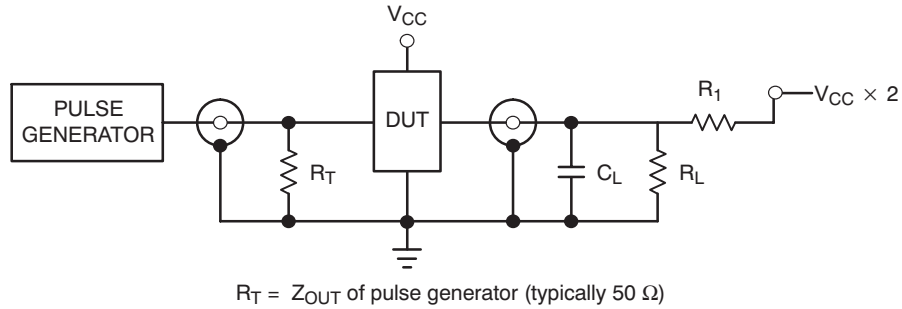
Figure 4. Test Circuit

DEVICE ORDERING INFORMATION

Device	Package	Shipping[†]
NL17SZ07DFT2	SOT−353/SC70−5/SC−88A	3000 / Tape & Reel
NL17SZ07DFT2G	SOT−353/SC70−5/SC−88A (Pb−Free)	3000 / Tape & Reel
NL17SZ07XV5T2	SOT−553	4000 / Tape & Reel
NL17SZ07XV5T2G	SOT−553 (Pb−Free)	4000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NL17SZ07

PACKAGE DIMENSIONS

SC−88A, SOT−353, SC−70
CASE 419A−02
ISSUE J
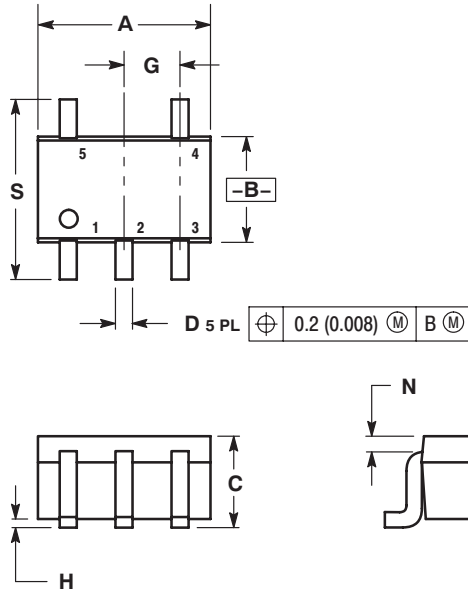
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 419A−01 OBSOLETE. NEW STANDARD 419A−02.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65 BSC	
H	---	0.004	---	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20

D 5 PL ⊕ 0.2 (0.008) Ⓜ B Ⓜ

SOLDERING FOOTPRINT*

$\frac{0.50}{0.0197}$

$\frac{0.65}{0.025}$

$\frac{0.65}{0.025}$

$\frac{0.40}{0.0157}$

$\frac{1.9}{0.0748}$

SCALE 20:1 $\left(\frac{mm}{inches}\right)$

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOT−553, 5 LEAD
CASE 463B−01
ISSUE B
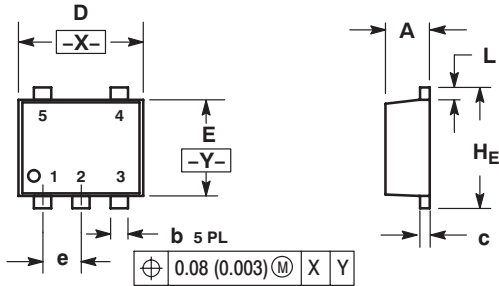
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
c	0.08	0.13	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.063	0.067
E	1.10	1.20	1.30	0.043	0.047	0.051
e	0.50 BSC			0.020 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
H_E	1.50	1.60	1.70	0.059	0.063	0.067

SOLDERING FOOTPRINT*

SCALE 20:1 $\left(\dfrac{mm}{inches}\right)$

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